



CHENMKO ENTERPRISE CO.,LTD

Halogens free devices

SURFACE MOUNT FAST SWITCHING DIODE

VOLTAGE RANGE 90 Volts CURRENT 130 mAmpere

LL73GP

FEATURES

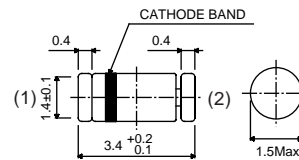
- * For surface mounted applications
- * Low profile package
- * Built-in strain relief
- * Low power loss, high efficiency
- * High current capability, low forward voltage drop
- * Power dissipation: 300mW
- * Repetitive peak forward current: 400mA
- * High temperature soldering guaranteed : 260°C/10 seconds at terminals

MECHANICAL DATA

Case: JEDEC Mini Melf molded plastic
Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end



Mini-Melf



Dimensions in millimeters

CIRCUIT



MAXIMUM RATINGS (At TA = 25°C unless otherwise noted)

RATINGS		SYMBOL	LL73GP	UNITS
Maximum Recurrent Peak Reverse Voltage		VRRM	90	Volts
Maximum RMS Voltage		VRMS	63	Volts
Maximum DC Blocking Voltage		VDC	90	Volts
Maximum Average Forward Rectified Current at TL = 100°C		IO	130	mAmps
Non-Repetitive Peak Forward Surge Current	@ t=1.0uS	IFSM	2.0	Amps
	@ t=1.0S		0.6	
Typic Junction Capacitance (Note 2)		CJ	2.0	pF
Maximum Reverse Recovery Time (Note 3)		TRR	4.0	nS
Typical Thermal Resistance (Note 1)		R θJA	625	°C / W
Storage and Operating Temperature Range		TJ, TSTG	-65 to +175	°C

ELECTRICAL CHARACTERISTICS (At TA = 25°C unless otherwise noted)

CHARACTERISTICS		SYMBOL	LL73GP	UNITS
Maximum Instantaneous Forward Voltage	@ IF = 50 mA	VF	1.00	Volts
	@ IF = 100 mA		1.20	Volts
Maximum Average Reverse Current at Rated DC Blocking Voltage	@ TA = 25°C	IR	0.5	uAmps
	@ TJ = 100°C		75	uAmps

NOTES : 1. Thermal Resistance (Junction to Lead) : PC Board Mounted on 0.06 X 0.06" (0.15X 0.15mm) copper pad area.
 2. Measured at 1.0 MHz and applied reverse voltage of 0.5 volt.
 3. IF=10 mA, VR=6.0V IRR=0.1XIR, RL=50 ohms

RATING CHARACTERISTIC CURVES (LL73GP)

FIG. 1 - TYPICAL FORWARD CURRENT DERATING CURRENT

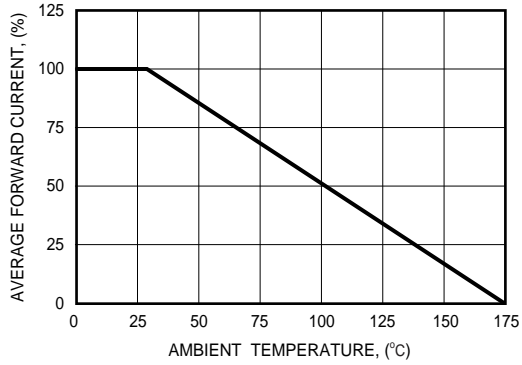


FIG. 2 - FORWARD CHARACTERISTICS

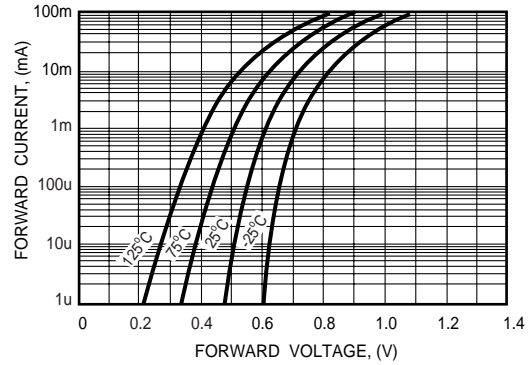


FIG. 3 - REVERSE CHARACTERISTICS

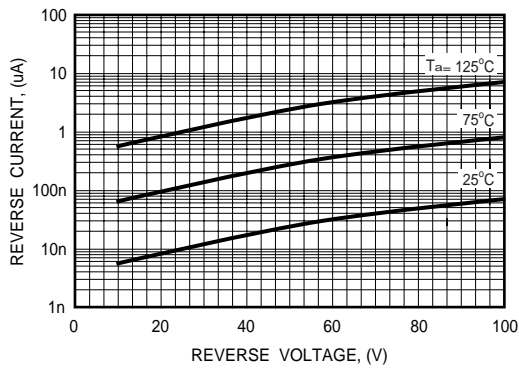


FIG. 4 - TYPICAL JUNCTION CAPACITANCE

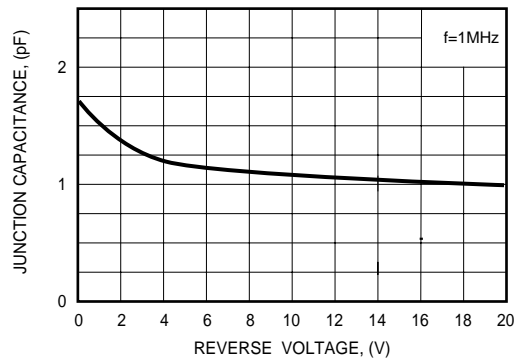


FIG. 5 - REVERSE RECOVERY TIME

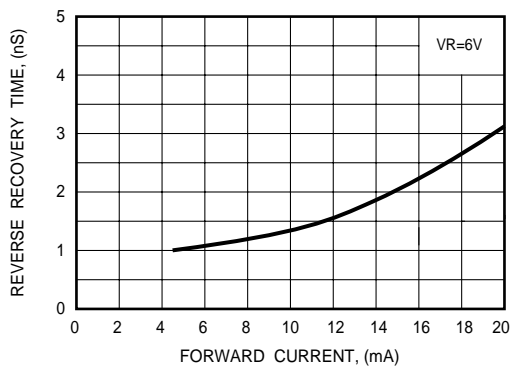


FIG. 6 - REVERSE RECOVERY TIME MEASUREMENT CIRCUIT

